

MECHANICAL CASE OUTLINE

PACKAGE DIMENSIONS

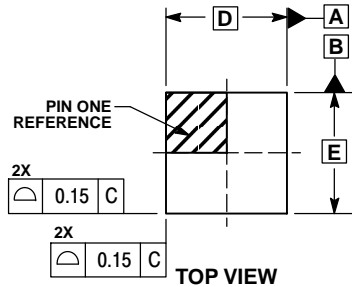
ON Semiconductor®



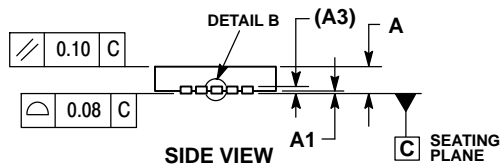
SCALE 2:1

QFN20, 4x4, 0.5P
CASE 485E
ISSUE C

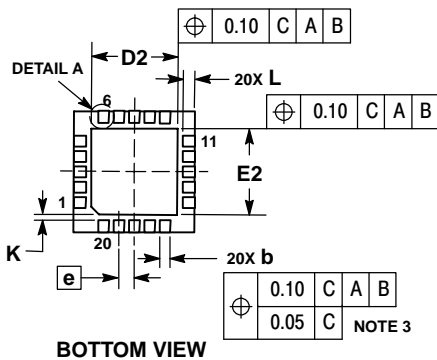
DATE 13 FEB 2018



TOP VIEW

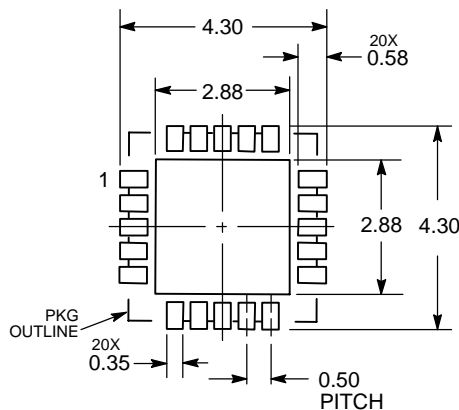


SIDE VIEW



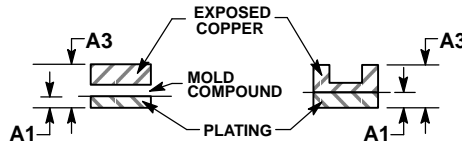
BOTTOM VIEW

SOLDERING FOOTPRINT*

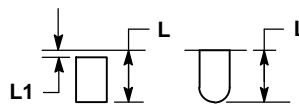


DIMENSIONS: MILLIMETERS

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.



DETAIL B
ALTERNATE
CONSTRUCTIONS



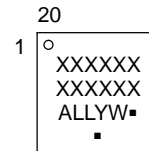
DETAIL A
OPTIONAL CONSTRUCTIONS

NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30 MM FROM THE TERMINAL TIP.
4. COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.

MILLIMETERS		
DIM	MIN	MAX
A	0.80	1.00
A1	---	0.05
A3	0.20	REF
b	0.20	0.30
D	4.00	BSC
D2	2.60	2.90
E	4.00	BSC
E2	2.60	2.90
e	0.50	BSC
K	0.20	REF
L	0.35	0.45
L1	0.00	0.15

GENERIC MARKING DIAGRAM*



XXXXXX= Specific Device Code

A = Assembly Location

LL = Wafer Lot

Y = Year

W = Work Week

▪ = Pb-Free Package

(Note: Microdot may be in either location)

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present. Some products may not follow the Generic Marking.

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STATUS:	ON SEMICONDUCTOR STANDARD	
NEW STANDARD:		
DESCRIPTION:	QFN20, 4X4, 0.5P	PAGE 1 OF 2

